

## Amendments to Specification

Rewrite the Abstract as follows:

~~Provided herein is a system architecture of~~ A semiconductor manufacturing equipment, wherein degas chamber(s) are integrated to the conventional pass-through chamber location. ~~Also provided herein is a system/method~~ A preferred embodiment for depositing Cu barrier and seed layers on a semiconductor wafer. ~~This system~~ comprises a front opening unified pod(s), a single wafer loadlock chamber(s), a degas chamber(s), a preclean chamber(s), a Ta or TaN process chamber(s), and a Cu process chamber(s). The degas chamber is integrated to a pass-through chamber. Such system may achieve system throughput higher than 100 wafers per hour.

Insert the following sentence at the beginning of the specification:

This patent application is a divisional of application no. 09/680,984 filed 10/5/2000.

Rewrite the paragraph at page 3, line 17 – page 4, line 3 as follows:

1           In still another aspect of the present invention, there is provided ~~is~~ a method of depositing Cu  
2   barrier and seed layers on a semiconductor wafer using the above-described system. This method  
3   comprises the steps of (1) loading the wafer to the degas chamber from the front opening unified pod  
4   through the single wafer loadlock chamber; (2) performing degas processing on the wafer in the degas  
5   chamber; (3) removing native oxide from the wafer surface in the preclean chamber; (4) depositing Ta  
6   or TaN on the wafer in the Ta or TaN process chamber; (5) passing the processed wafer through the  
7   degas chamber; (6) depositing Cu seed layer on the wafer in the Cu process chamber; and (7)  
8   transferring the processed wafer from the Cu process chamber to the front opening unified pod  
9   through the single wafer loadlock chamber, thereby obtaining a wafer with Cu barrier and seed layer  
10   deposition.

Rewrite the paragraph at page 4, lines 14–23, as follows:

So that the matter in which the above-recited features, advantages and objects of the invention, as well as others which will become clear, are attained and can be understood in detail, more particular descriptions of the invention briefly summarized above ~~may be had~~ are provided by reference to certain embodiments thereof which are illustrated in the appended drawings. These drawings form a part of the specification. It is to be noted, however, that the appended drawings illustrate embodiments of the invention and therefore are not to be considered limiting in their scope.